



PATENT  
YO996-184 IBM-219

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of	:	D.Y. Shih, et al.
Serial Number	:	09/254,769
Filing Date	:	March 11, 1999
Examiner	:	V. Nguyen
Group Art Unit	:	2858
For	:	WAFER SCALE HIGH DENSITY PROBE ASSEMBLY, APPARATUS FOR USE THEREOF AND METHODS OF FABRICATION THEREOF

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of 1321

Honorable Commissioner of Patents  
and Trademarks  
Washington, D.C. 20231

Sir:

In response to the Official Action dated December 7, 2000, please amend the above-identified application as follows:

IN THE SPECIFICATION:

Page 12, after line 11, insert as a separate paragraph:

-- Figure 6a depicts an alternate embodiment of Figure 6. Sheet 20 comprises two distinct layers 20a, a dielectric material, e.g. a polymer such as polyimide and 20b which is an electrically conducting layer of metal. This composite sheet 20a and 20b in Figure 6a has a plurality (not shown) of openings 21 (holes) therethrough of the type depicted. Ball 16 is insulated from contacting the metallic sheet 20b by the dielectric material extending into opening 21. --

TO 2800 MAIL ROOM

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